



3M™ Textool™ BGA/LGA LOW CLOSING FORCE LIDDED SOCKETS, 1.27mm TYPE II

Low Profile Version

Solution provided by: **3M**

- Modular construction allows for cost effective socket proliferation for standard and custom packages
- Coarse alignment on device body followed by a secondary fine alignment to the solder balls
- Flat contact head that provides for minimum solder ball deformation
- Can be adapted to either BGA or LGA formats
- Built-in alignment plates
- Available with inserts for mounting screws (screws not included with socket)
- Lid closing force reduction ration of 13 to 1
- Accepts maximum pin count of 729 and maximum package thickness of 3.50mm
- Low profile lid reduces total socket height
- Recommended for sockets with lead counts of >300
- Thru hole design



DESCRIPTION & ORDERING INFORMATION

A XXX - X - 1386 - XX - X X 0 1

